

DB2J208

Silicon epitaxial planar type

For super high speed switching circuits

■ Features

- Low forward voltage V_F
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
SMini2-F5-B
- Pin Name
1: Cathode
2: Anode

■ Marking Symbol: B8

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|--|-------------|-------------|------------------|
| Reverse voltage | V_R | 20 | V |
| Repetitive peak reverse voltage | V_{RRM} | 25 | V |
| Forward current (Average)*1 | $I_{F(AV)}$ | 500 | mA |
| Non-repetitive peak forward surge current *2 | I_{FSM} | 2 | A |
| Junction temperature | T_j | 125 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +125 | $^\circ\text{C}$ |

Note) *1: Mounted on an alumina PC board

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

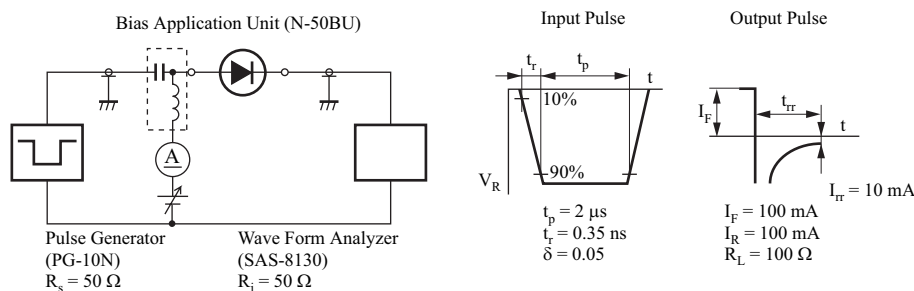
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------|----------|--|-----|-----|------|---------------|
| Forward voltage | V_F | $I_F = 500 \text{ mA}$ | | | 0.42 | V |
| Reverse current | I_R | $V_R = 20 \text{ V}$ | | | 200 | μA |
| Terminal capacitance | C_t | $V_R = 10 \text{ V}, f = 1 \text{ MHz}$ | | 12 | | pF |
| Reverse recovery time * | t_{rr} | $I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$ | | 4.3 | | ns |

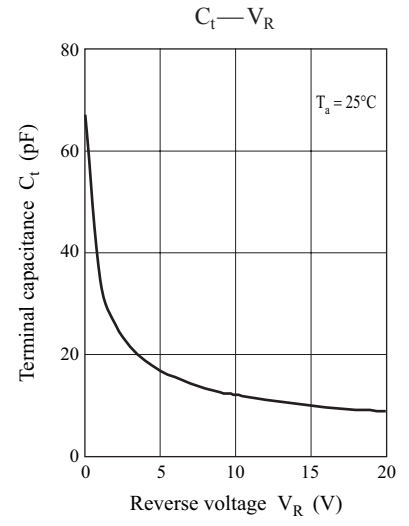
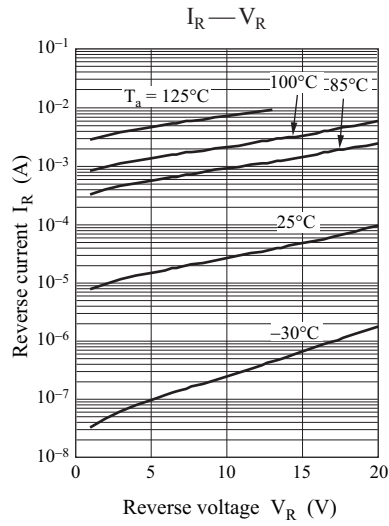
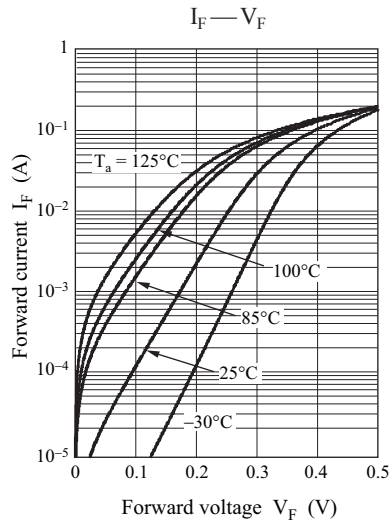
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz

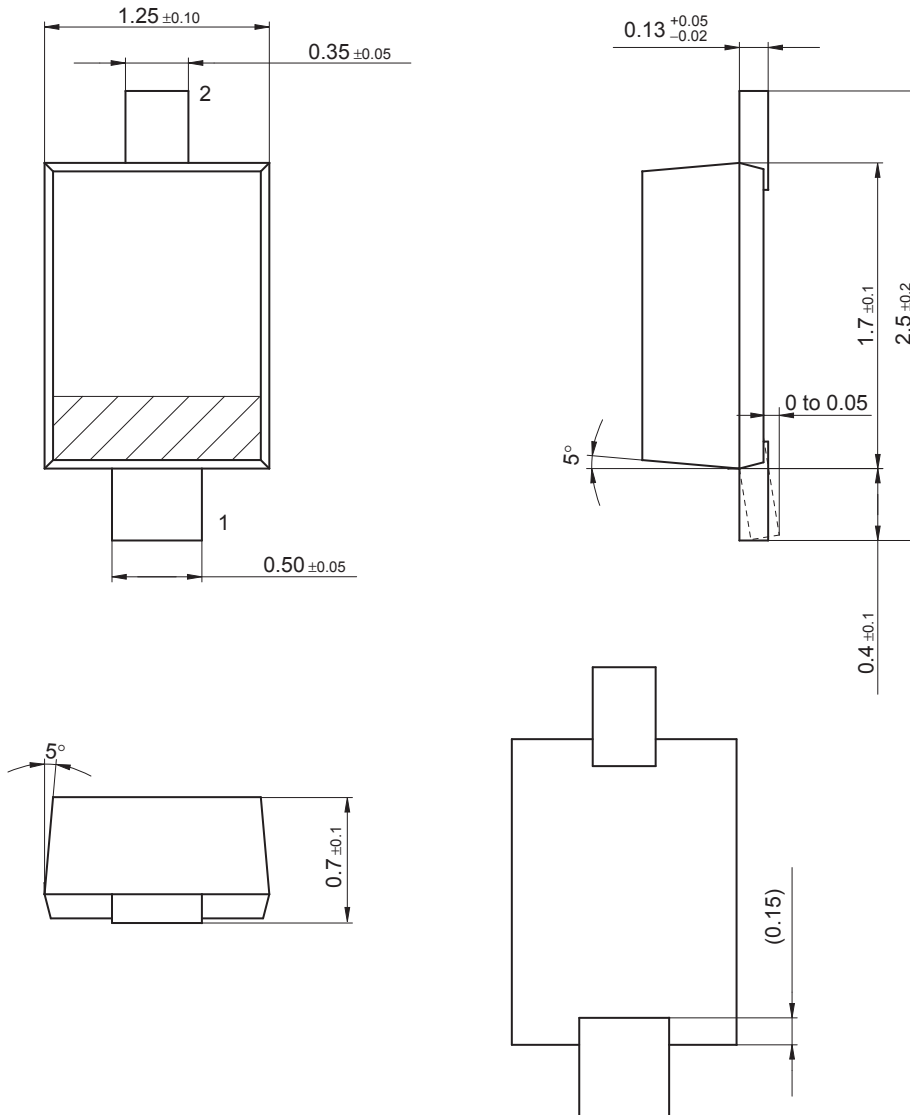
*: t_{rr} measurement circuit





SMini2-F5-B

Unit: mm



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